AN ELLSWORTH ADHESIVES COMPANY

Product Spotlight EPI350

ResinLab® EP1350 Black is our highest performing electronic potting and encapsulating compound. It has a unique cycloaliphatic epoxy base chemistry that provides a very high Tg, low CTE, and superior electrical insulation properties under extreme conditions. It is highly filled providing low shrinkage upon cure as well as high thermal conductivity. ResinLab® also offers a clear unfilled version with some of the same high performance properties.

EP1350 Features & Benefits:

- Very high Tg with impressive compressive strength even over 200 $^{\circ}\mathrm{C}$
- Low mixed viscosity with long pot life for batch mixing and vacuum impregnation
- High thermal conductivity with very low CTE and low shrinkage
- Extremely tough polymer with high resistance to thermal cycling as well as UV stability
- Low ionic content and relatively low cost for very high performance

For more information on ResinLab® EP1350 contact



EP1350 is available in:

Quart kits Gallon kits Pail kits



EP1350 Properties:

Viscosity	Glass Transition Temp
6,000 cps	203 °C
Hardness	Coefficient of Thermal Expansion
90 Shore D	46 ppm below Tg
Tensile Modulus	Pot Life
635,000 psi	12 to 16 hours

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